



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



DESCRIPTION

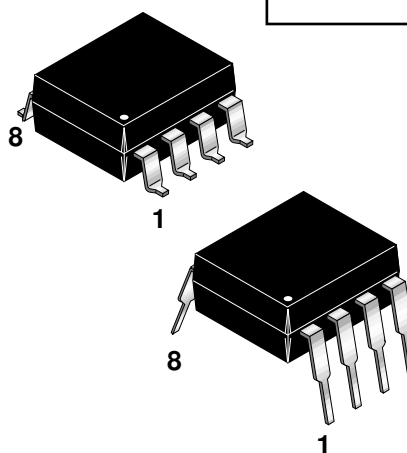
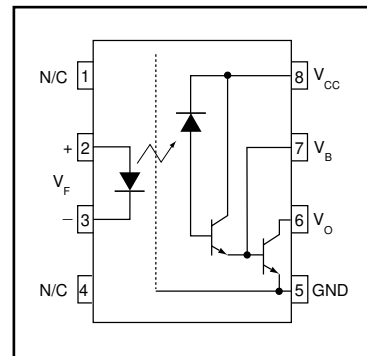
The CNW138 and CNW139 are high isolation voltage optocouplers, comprising an infrared emitting AlGaAs diode, optically coupled to a high gain split Darlington photodetector in an 8-pin wide body dual-in-line package (DIP).

FEATURES

- Wide body DIL encapsulation, with a pin distance of 10.16 mm
- Minimum clearance of 9.6 mm and minimum creepage of 10 mm
- High current transfer ratio
- Short propagation delay times
- TTL compatible
- Low saturation voltage
- High transient immunity
- Maximum permissible voltage of 8000 V (peak) and maximum operating isolation voltage of 1000 V (RMS) in accordance with VDE 00884
- UL recognized (File # E90700)

APPLICATIONS

- Line receivers
- Logic families ground isolation
- Low power systems
- Line voltage status indicator.



| ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$ unless otherwise specified) | | | | |
|--|-----------|--------|----------------|------------------|
| Parameters | Symbol | Device | Value | Units |
| TOTAL DEVICE | | | | |
| Storage Temperature | T_{STG} | All | -55 to +150 | $^\circ\text{C}$ |
| Operating Temperature | T_{OPR} | All | -55 to +85 | $^\circ\text{C}$ |
| Lead Solder Temperature | T_{SOL} | All | 260 for 10 sec | $^\circ\text{C}$ |
| EMITTER | | | | |
| Continuous Forward Current (DC) | I_F | All | 100 | mA |
| Reverse Voltage (DC) | V_R | All | 5 | V |
| Forward Current - Peak (1 μs pulse, $f = 300$ Hz) | $I_F(pk)$ | All | 1 | A |
| LED Power Dissipation (up to $T_A = 70^\circ\text{C}$) | P_D | All | 250 | mW |
| DETECTOR | | | | |
| Collector Current (DC) | I_C | All | 60 | mA |
| Output Voltage (pins 6 & 5) | V_O | CNW138 | -0.5 to 7 | V |
| | | CNW139 | -0.5 to 18 | |
| Supply Voltage (pins 8 & 5) | V_{CC} | CNW138 | -0.5 to 7 | V |
| | | CNW139 | -0.5 to 18 | |
| Emitter-Base Voltage (pins 7 & 5) | V_{EBO} | All | 5 | V |
| Total Power Dissipation (up to $T_A = 70^\circ\text{C}$) | P_D | All | 100 | mW |

| ELECTRICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$ Unless otherwise specified) | | | | | | | |
|--|--|------------|--------|------|------|-----|---------------|
| INDIVIDUAL COMPONENT CHARACTERISTICS | | | | | | | |
| Parameter | Test Conditions | Symbol | Device | Min | Typ* | Max | Unit |
| EMITTER Forward Voltage | $I_F = 1.6 \text{ mA}$ | V_F | All | 1.25 | 1.5 | 1.7 | V |
| | $I_F = 1.6 \text{ mA}, T_A = 0 \text{ to } 70^\circ\text{C}$ | | | 1.1 | | 1.8 | |
| Input Reverse Current | $V_R = 5 \text{ V}$ | I_R | All | | | 10 | μA |
| | $V_R = 5 \text{ V}, T_A = 0 \text{ to } 70^\circ\text{C}$ | | | | | 100 | |
| Diode Capacitance | $V_D = 0, f = 1 \text{ MHz}$ | C_d | All | | 200 | | pF |
| DETECTOR Collector-Emitter Breakdown Voltage | $I_C = 1 \text{ mA}$ | BV_{CEO} | CNW138 | 7 | | | V |
| | | | CNW139 | 18 | | | |
| Emitter-Base Breakdown Voltage | $I_C = 0.1 \text{ mA}$ | BV_{EBO} | All | 0.5 | | | V |
| Logic High Output Current | $I_F = 0, V_O = V_{CC} = 7 \text{ V}, T_A = 0 \text{ to } 70^\circ\text{C}$ | I_{OH} | CNW138 | | 0.05 | 250 | μA |
| | $I_F = 0, V_O = V_{CC} = 18 \text{ V}, T_A = 0 \text{ to } 70^\circ\text{C}$ | | CNW139 | | 0.1 | 100 | |
| Logic High Supply Current | $I_F = 0, I_O = 0, V_{CC} = 18 \text{ V}, T_A = 0 \text{ to } 70^\circ\text{C}$ | I_{CCH} | All | | 0.01 | 1 | μA |
| Logic Low Supply Current | $I_F = 1.6 \text{ mA}, I_O = 0, V_{CC} = 18 \text{ V}, T_A = 0 \text{ to } 70^\circ\text{C}$ | I_{CCL} | All | | 0.5 | 2 | mA |

| ISOLATION CHARACTERISTICS | | | | | | | |
|-------------------------------------|--|------------|-----------|-----------|-----|----------|--|
| Characteristic | Test Conditions | Symbol | Min | Typ* | Max | Units | |
| Isolation Capacitance | $V_{I-O} = 0 \text{ V}, f = 1 \text{ MHz}$ | C_{ISO} | | 0.4 | 0.6 | pF | |
| Isolation Resistance | $V_{I-O} = \pm 500 \text{ V (DC)}$ | R_{ISO} | 10^{12} | 10^{13} | | Ω | |
| Input-Output Isolation Voltage | T = 1 min. (Peak value) | V_{ISO} | 7070 | | | V | |
| | T = 1 min. (RMS value) | | 5000 | | | | |
| Maximum Operating Isolation Voltage | RMS value | V_{IORM} | 1000 | | | V | |

| TRANSFER CHARACTERISTICS ($T_A = 25^\circ\text{C}$ Unless otherwise specified) | | | | | | | |
|--|--|----------|--------|-----|------|-----|------|
| Parameter | Test Conditions | Symbol | Device | Min | Typ* | Max | Unit |
| TOTAL DEVICE Current Transfer Ratio | $I_F = 1.6 \text{ mA}, V_O = 0.4 \text{ V}, V_{CC} = 4.5 \text{ V}, T_A = 0 \text{ to } 70^\circ\text{C}, \text{DC}$ | CTR | CNW138 | 300 | | | % |
| | | | CNW139 | 500 | | | |
| | $I_F = 0.5 \text{ mA}, V_O = 0.4 \text{ V}, V_{CC} = 4.5 \text{ V}, T_A = 0 \text{ to } 70^\circ\text{C}, \text{DC}$ | | CNW139 | 400 | | | |
| Logic Low Output Voltage | $I_F = 1.6 \text{ mA}, I_C = 4.8 \text{ mA}, V_{CC} = 4.5 \text{ V}, T_A = 0 \text{ to } 70^\circ\text{C}$ | V_{OL} | CNW138 | | | 0.4 | V |
| | $I_F = 1.6 \text{ mA}, I_C = 8 \text{ mA}, V_{CC} = 4.5 \text{ V}, T_A = 0 \text{ to } 70^\circ\text{C}$ | | CNW139 | | | 0.4 | |
| | $I_F = 5 \text{ mA}, I_C = 15 \text{ mA}, V_{CC} = 4.5 \text{ V}, T_A = 0 \text{ to } 70^\circ\text{C}$ | | | | | 0.4 | |
| | $I_F = 12 \text{ mA}, I_C = 24 \text{ mA}, V_{CC} = 4.5 \text{ V}, T_A = 0 \text{ to } 70^\circ\text{C}$ | | | | | 0.4 | |

* Typical values at $T_A = 25^\circ\text{C}$

| SWITCHING CHARACTERISTICS ($T_A = 25^\circ\text{C}$ Unless otherwise specified) | | | | | | | |
|---|--|-----------|--------|-----|------|-----|---------------|
| Parameter | Test Conditions | Symbol | Device | Min | Typ* | Max | Unit |
| Propagation delay time to logic low at output (Fig. 1) | $R_L = 2.2\text{ k}\Omega, I_F = 1.6\text{ mA}, V_{CC} = 5\text{ V}$ | T_{PHL} | All | | 1.5 | 10 | μs |
| | $R_L = 2.2\text{ k}\Omega, I_F = 1.6\text{ mA}, V_{CC} = 5\text{ V}, 0\text{ to }70^\circ\text{C}$ | | | | | 11 | |
| | $R_L = 4.7\text{ k}\Omega, I_F = 0.5\text{ mA}, V_{CC} = 5\text{ V}$ | | | | 4 | 25 | |
| | $R_L = 4.7\text{ k}\Omega, I_F = 0.5\text{ mA}, V_{CC} = 5\text{ V}, 0\text{ to }70^\circ\text{C}$ | | | | | 30 | |
| | $R_L = 270\ \Omega, I_F = 12\text{ mA}, V_{CC} = 5\text{ V}$ | | | | 0.5 | 1 | |
| | $R_L = 270\ \Omega, I_F = 12\text{ mA}, V_{CC} = 5\text{ V}, 0\text{ to }70^\circ\text{C}$ | | | | | 1.1 | |
| Propagation delay time to logic high at output (Fig. 1) | $R_L = 2.2\text{ k}\Omega, I_F = 1.6\text{ mA}, V_{CC} = 5\text{ V}$ | T_{PLH} | All | | 10 | 35 | μs |
| | $R_L = 2.2\text{ k}\Omega, I_F = 1.6\text{ mA}, V_{CC} = 5\text{ V}, 0\text{ to }70^\circ\text{C}$ | | | | | 70 | |
| | $R_L = 4.7\text{ k}\Omega, I_F = 0.5\text{ mA}, V_{CC} = 5\text{ V}$ | | | | 20 | 60 | |
| | $R_L = 4.7\text{ k}\Omega, I_F = 0.5\text{ mA}, V_{CC} = 5\text{ V}, 0\text{ to }70^\circ\text{C}$ | | | | | 115 | |
| | $R_L = 270\ \Omega, I_F = 12\text{ mA}, V_{CC} = 5\text{ V}$ | | | | 2.0 | 7 | |
| | $R_L = 270\ \Omega, I_F = 12\text{ mA}, V_{CC} = 5\text{ V}, 0\text{ to }70^\circ\text{C}$ | | | | | 11 | |

| TRANSIENT IMMUNITY (see Fig. 2 and note 1) | | | | | | | |
|---|--|--------|--------|------|------|-----|-------------------------|
| Parameter | Test Conditions | Symbol | Device | Min | Typ* | Max | Unit |
| Common mode transient immunity at logic high | $R_L = 2.2\text{ k}\Omega, I_F = 0, V_{CC} = 5\text{ V}, V_{CM} = 10\text{ V}_{(p-p)}$ | CMH | All | 0.5 | | | $\text{kV}/\mu\text{s}$ |
| Common mode transient immunity at logic low | $R_L = 2.2\text{ k}\Omega, I_F = 1.6\text{ mA}, V_{CC} = 5\text{ V}, V_{CM} = 10\text{ V}_{(p-p)}$ | CML | All | -0.5 | | | $\text{kV}/\mu\text{s}$ |
| Common mode rejection ratio | $R_L = 100\ \Omega, I_C = 45\text{ mA}, f = 10\text{ kHz}, V_{CC} = 10\text{ V}$ | CMRR | All | | -65 | | dB |

Note

1. $R_{CC} (\text{k}\Omega) = 1\text{ V}/0.15\text{ I}_F (\text{mA})$, to protect the photodetector against high surge currents.

* Typical values at $T_A = 25^\circ\text{C}$

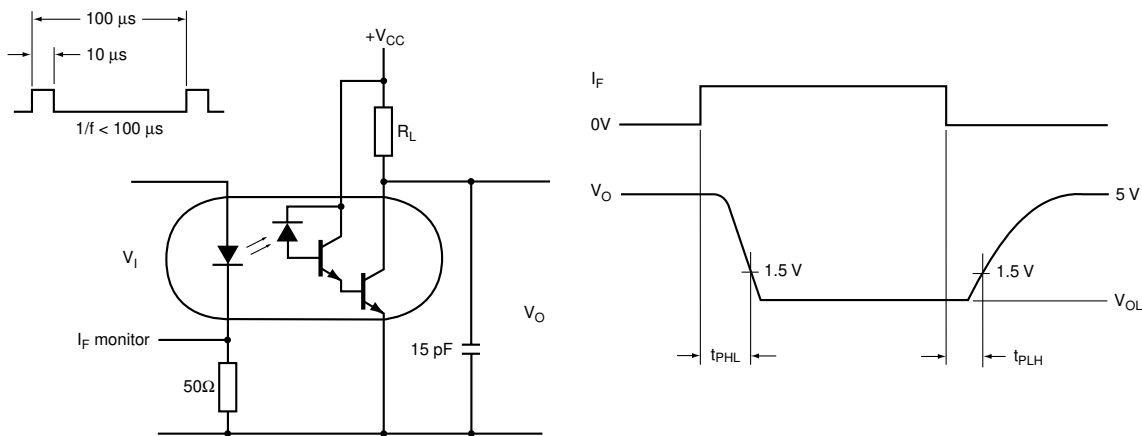


Fig. 1 Switching Times Test Circuit and Waveforms

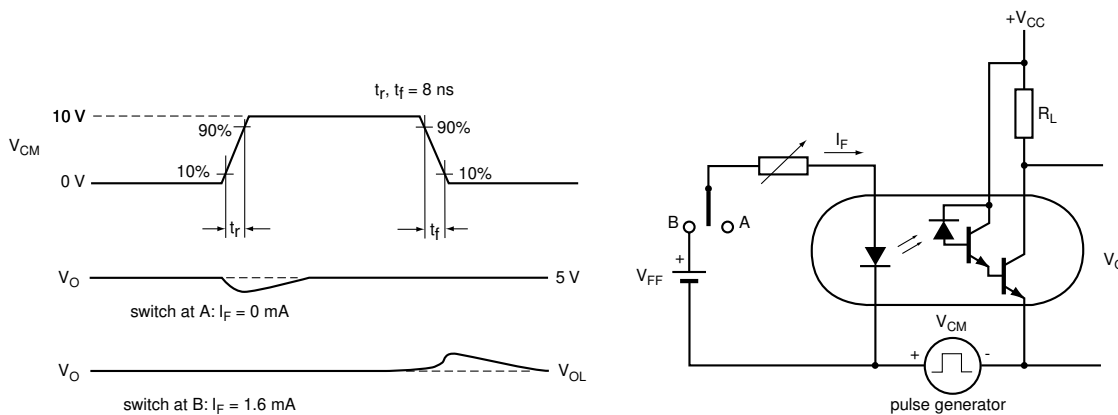


Fig. 2 Transient Immunity Test Circuit and Waveforms

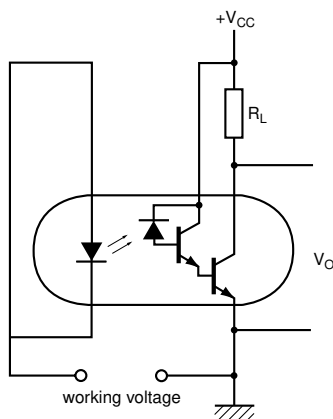


Fig. 3 Logic Output Current Test Circuit

Fig. 4 LED Forward Current vs. Forward Voltage

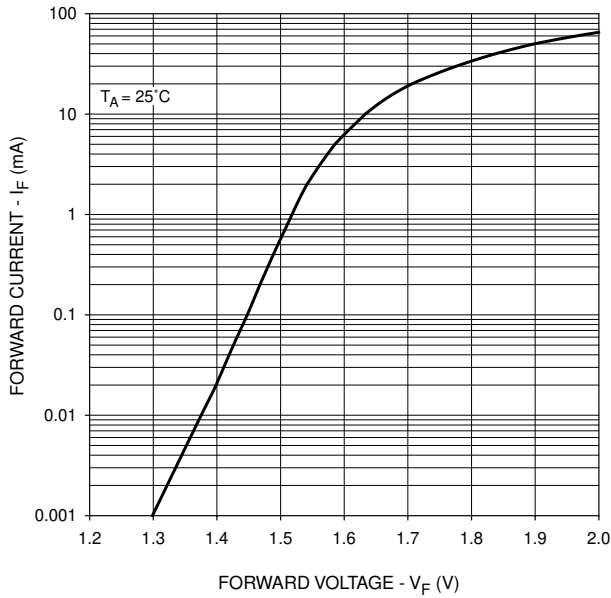


Fig. 5 Normalized Current Transfer Ratio vs. Forward Current

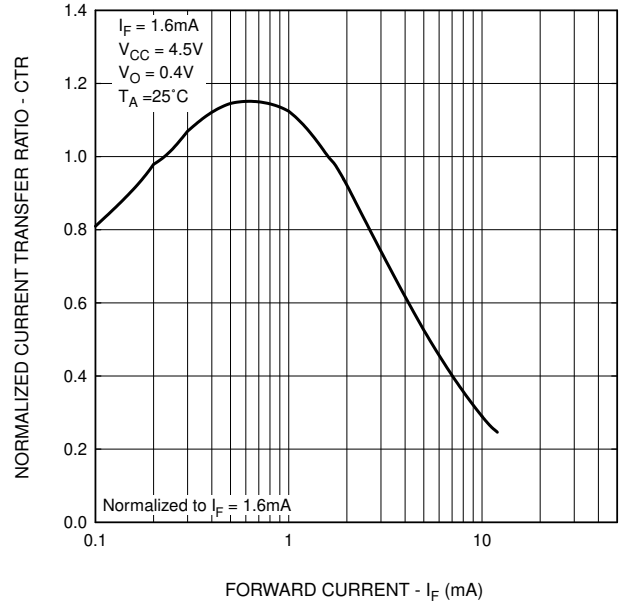


Fig. 6 Normalized Current Transfer Ratio vs. Ambient Temperature

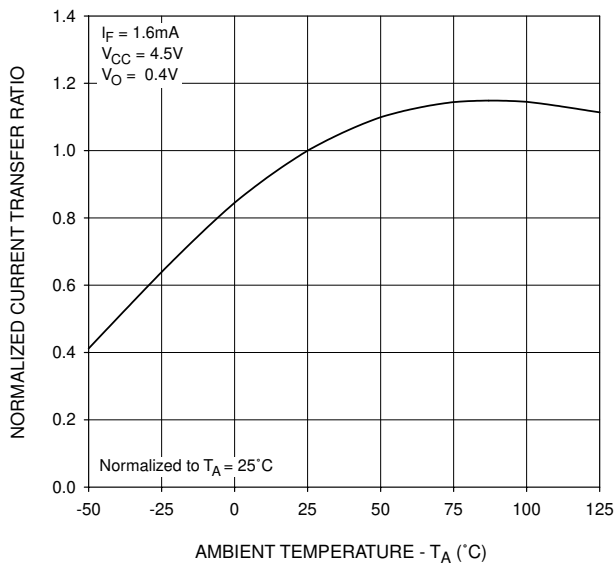


Fig. 7 Logic Low Supply Current vs. Forward Current

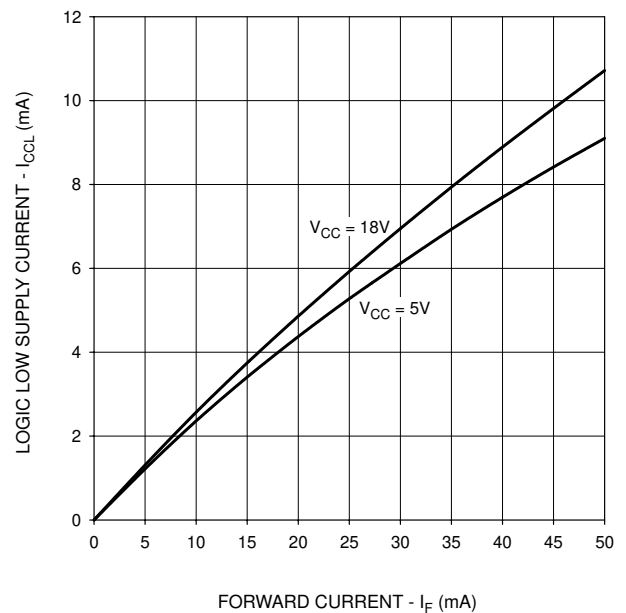


Fig. 8 Logic High Output Current vs. Ambient Temperature

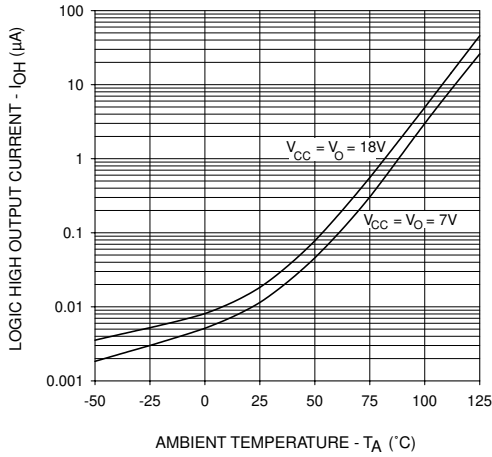


Fig. 9 Output Current vs. Output Voltage

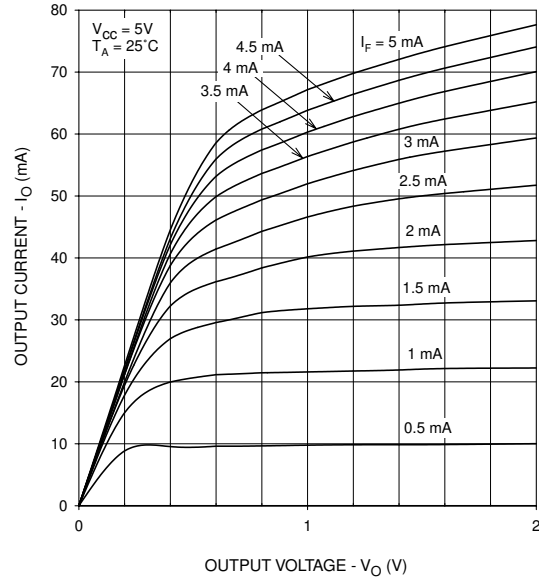


Fig. 10 Propagation Delay vs. Ambient Temperature

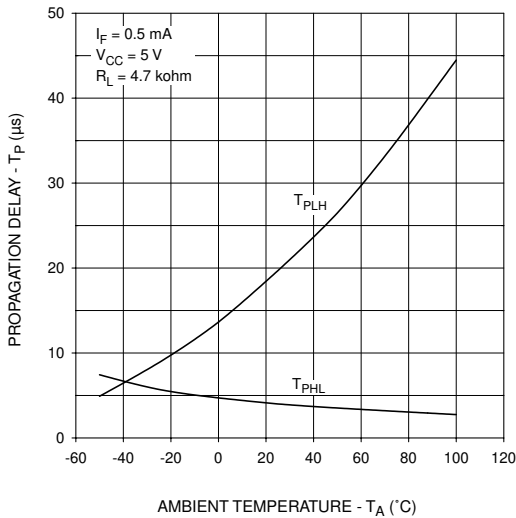


Fig. 11 Propagation Delay vs. Ambient Temperature

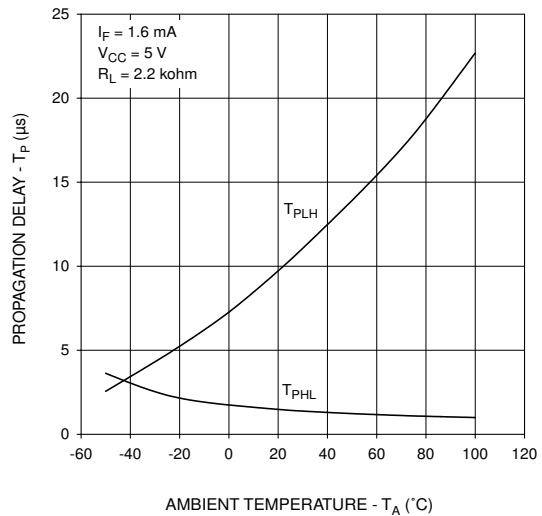
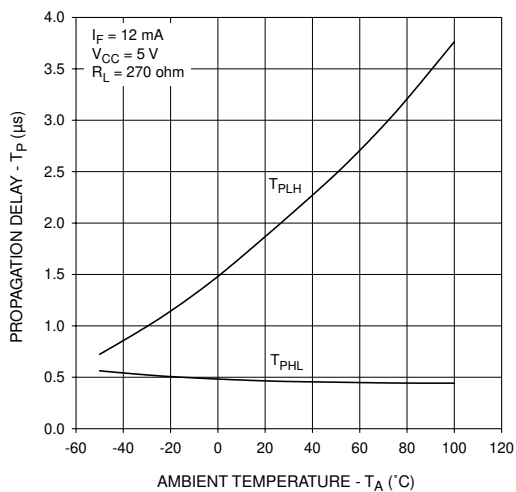
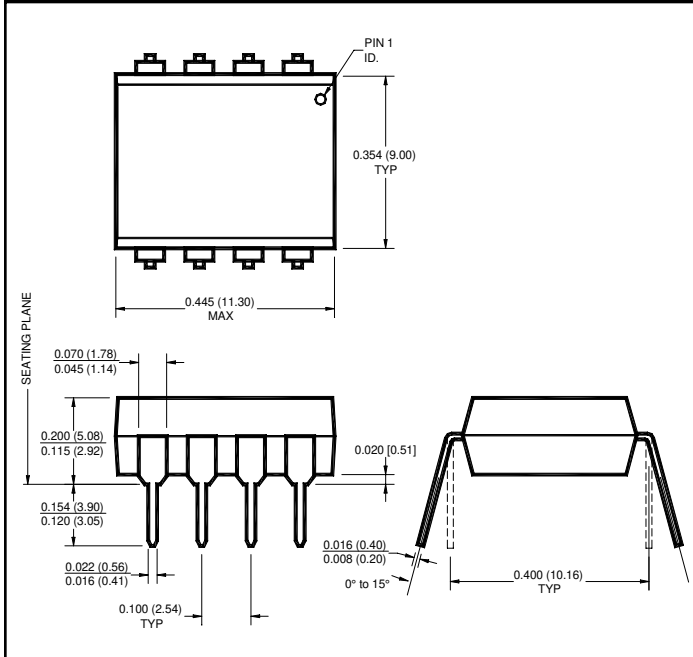


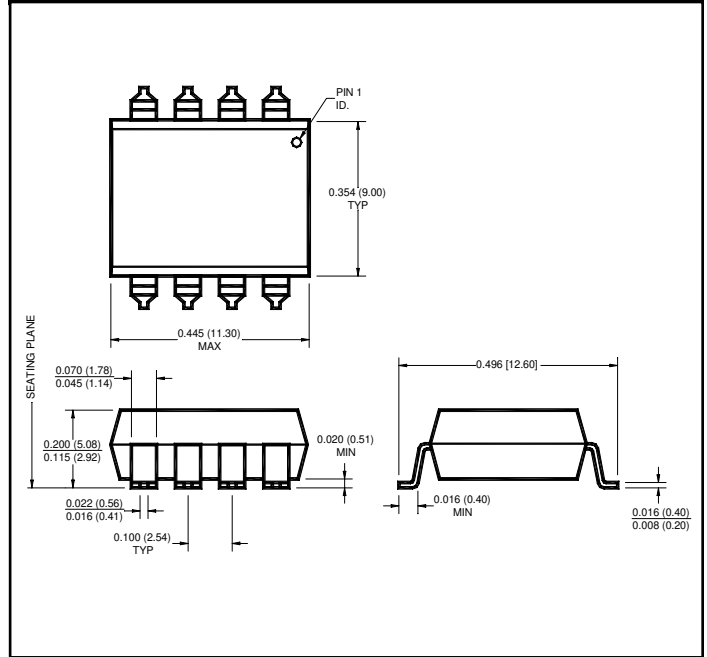
Fig. 12 Propagation Delay vs. Ambient Temperature



Package Dimensions (Through Hole)



Package Dimensions (Surface Mount)



NOTE

All dimensions are in inches (millimeters)

ORDERING INFORMATION

| Option | Order Entry Identifier | Description |
|--------|------------------------|-------------------------|
| S | .S | Surface Mount Lead Bend |
| 300 | .300 | VDE 0884 |

DISCLAIMER

FAIRCHILD SEMICONDUCTOR RESERVES THE THE RIGHT TO MAKE CHANGES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION OR DESIGN. FAIRCHILD DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN; NEITHER DOES IT CONVEY ANY LICENSE UNDER ITS PATENT RIGHTS, NOR THE RIGHTS OF OTHERS.

LIFE SUPPORT POLICY

FAIRCHILD'S PRODUCTS ARE NOT AUTHORIZED FOR USE AS CRITICAL COMPONENTS IN LIFE SUPPORT DEVICES OR SYSTEMS WITHOUT THE EXPRESS WRITTEN APPROVAL OF THE PRESIDENT OF FAIRCHILD SEMICONDUCTOR CORPORATION. As used herein:

1. Life support devices or systems are devices or systems which, (a) are intended for surgical implant into the body, or (b) support or sustain life, and (c) whose failure to perform when properly used in accordance with instructions for use provided in labeling, can be reasonably expected to result in a significant injury of the user.
2. A critical component in any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.